



N-MOSFET 150V, $2.3m\Omega$, 193A

Features

- Uses advanced SGT technology
- Extremely low on-resistance RDS(on)
- Excellent gate charge x RDS(on) product(FOM)

Product Summary

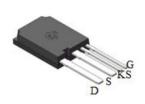
V _{DS}	150V
R _{DS(on)}	$2.3 m\Omega$
I _D	193A

100% DVDS Tested
100% Avalanche Tested

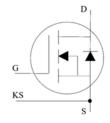


Application

- Motor control and drives
- Battery management
- DC/DC and AC/DC converter
- UPS







Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
SFG026N150I3	026N150I3	TO-247PLUS-4L	Tube	N/A	N/A	30pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Drain - Source Voltage	V _{DS}	150	V	
Gate - Source Voltage		V _G S	±20	V
Continuous Drain Current	T _C = 25°C (Package limited)		193	۸
Continuous Drain Current	T _C = 100°C (Package limited)	l _D	140	A
Pulsed Drain Current(Tc=25°C,tp li	I _{D,Pulse}	772	А	
Single Pulsed Avalanche Energy(Eas	2036	mJ	
Power Dissipation $T_C = 25^{\circ}C$		P _{tot}	446	W
Junction Temperature	TJ	-55~ +150	°C	
Storage Temperature	T _{STG}	-55~ +150	°C	





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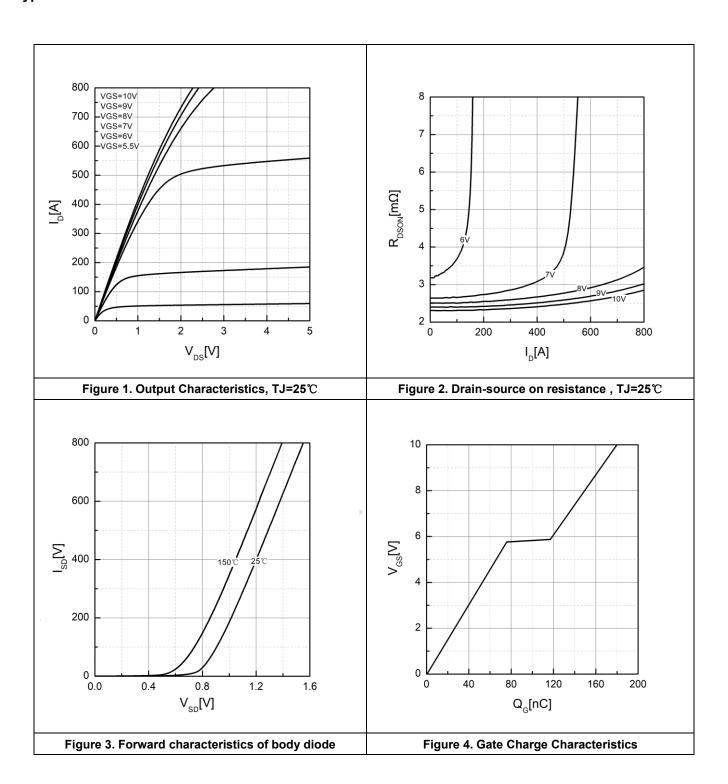
Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance , junction – case	R _{thJC}	0.28	°C/W
Thermal resistance , junction – ambient(min. footprint)	R _{thJA}	37	°C/W

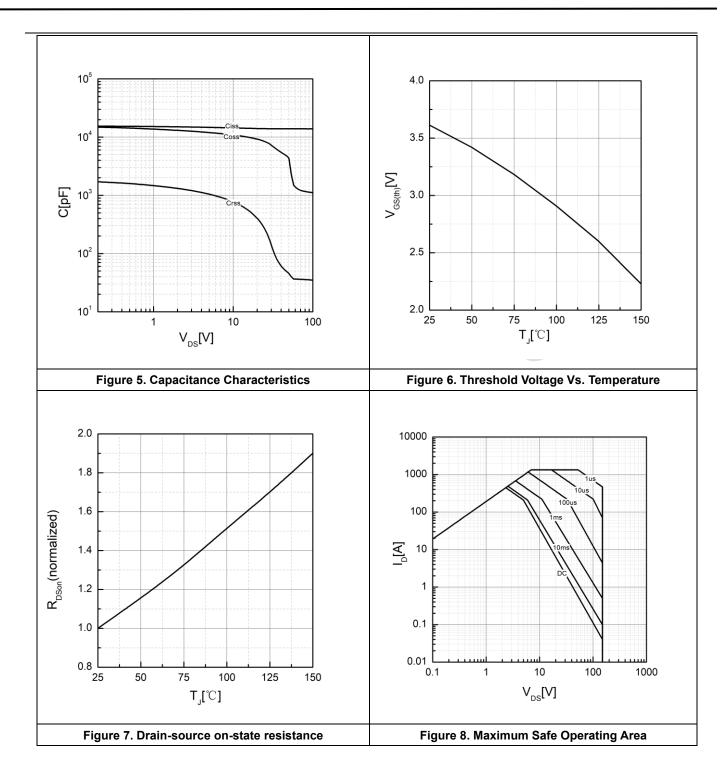
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic			1		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250µA	150	-	-	V
	V _{DS} =150V, V _{GS} = 0V, T _C = 25°C	-	-	1	μA	
IDSS	Drain-Source Leakage Current	V _{DS} =150V,V _{GS} = 0V, T _C = 55℃	-	-	10	μΑ
Igss	Gate-Source Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-100	-	100	nA
On Charac	cteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3	-	4.6	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D =100A	-	2.3	2.7	mΩ
g FS	Forward Transconductance	V _{DS} = 5V, I _D =100A	-	241	-	S
Dynamic (Characteristics			1		l .
Rg	Gate Resistance		-	1.3	-	Ω
Ciss	Input Capacitance	\\ 75\\\\ 0\\	-	13900	-	pF
Coss	Output Capacitance	$V_{DS} = 75V, V_{GS} = 0V,$ f = 1MHz	-	1180	-	pF
Crss	Reverse Transfer Capacitance		-	36	-	pF
Qg	Total Gate Charge	V _{DS} =75V, I _D = 100A, V _{GS} = 10V	-	180	-	nC
Q _{gs}	Gate-Source Charge		-	75	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	VGS - 10V	-	41	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	80	-	ns
tr	Turn-On Rise Time	V _{DD} = 75V, I _D = 100A,	-	40	-	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 1\Omega$, $V_{GS} = 10V$	-	150	-	ns
t _f	Turn-Off Fall Time		-	30	-	ns
Source-Dr	rain Diode Characteristics and Maxim	um Ratings		1		I.
Is	Maximum Continuous Diode Forward	Current	-	-	445	Α
I _{SM}	Maximum Pulsed Diode Forward Current		-	-	1335	Α
t _{rr}	Reverse Recovery Time	$T_J = 25^{\circ}C$, $I_S = 100A$, $V_{GS} = 0V$	-	150	-	ns
Qrr	Reverse Recovery Charge	di/dt = 150A/µs	-	1100	-	nC
V _{SD}	Source to Drain Diode Forward Voltage	T _J = 25°C, I _S = 100A, V _{GS} = 0V	-	0.90	-	٧



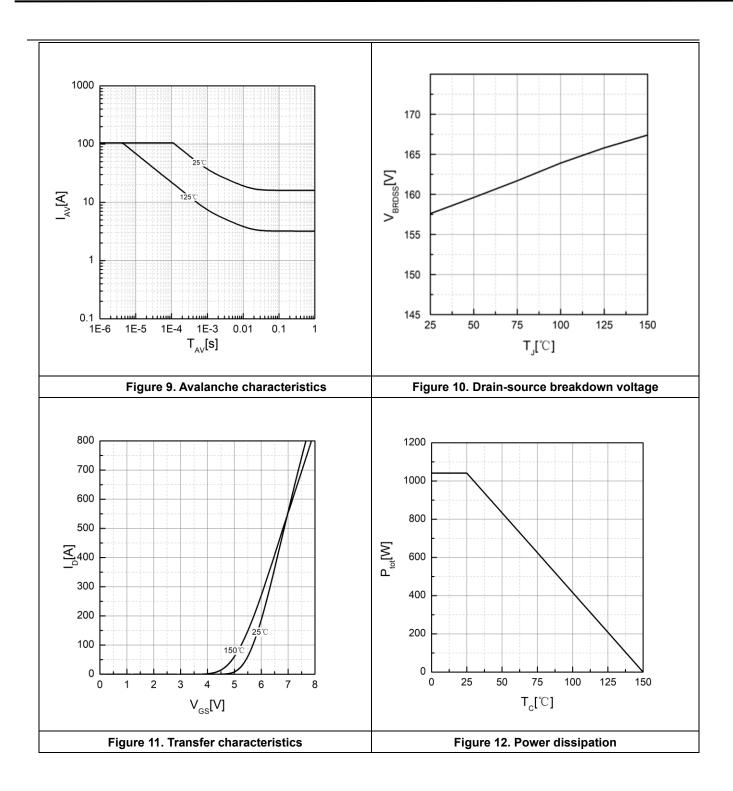
Typical Performance Characteristics



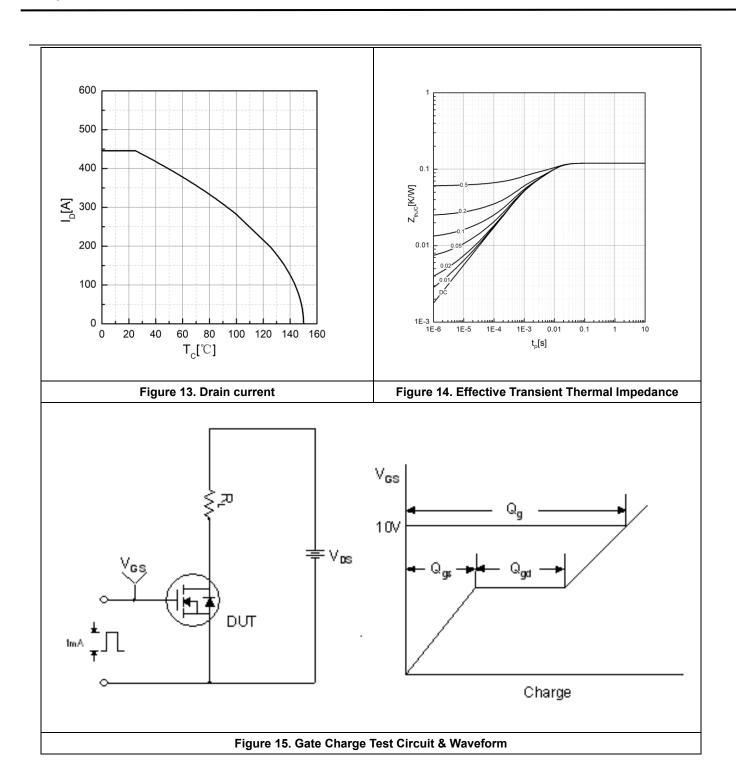




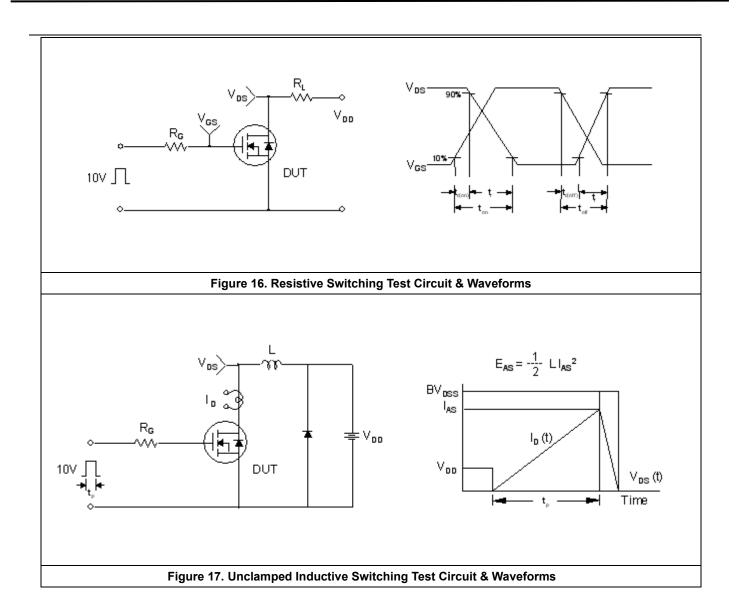






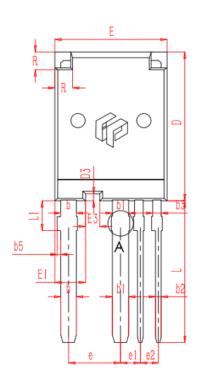


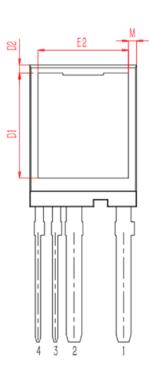


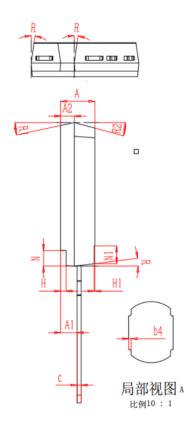




Package Outline TO247PLUS-4L







DIMENSIO	N MILLIMETERS			
DIMENSIC	MIN	NOM	MAX	
A	4. 95	5	5. 05	
A1	2.36	2.41	2.46	
A2	1. 95	2	2.05	
b	2. 15	2. 2	2. 25	
b1	2. 25	2. 3	2. 35	
b2	0.75	0.8	0.85	
b3	1. 15	1.2	1. 25	
b4		MAX0. 07		
b5	0.45	0.5	0.55	
c	0. 595	0.6	0.635	
D	20. 9	21	21.1	
D1	15.05	15. 55	16. 05	
D2	1. 15	1.2	1. 25	
D3	0.95	1	1.05	
E	15. 75	15.8	16. 85	
E1	4. 2	4. 33	4.4	
E2	13.3	13. 37	13.5	
E3	1. 95	2	2.05	
e		7. 32		
e1		2.79		
e2		2. 54		
Н	0.75	0.8	0.85	
H1	0.05	0.1	0. 15	
L	19.9	20	20. 1	
L1	4. 1	4. 2	4.3	
M	1. 17	1. 22	1. 27	
N	2. 2	1. 22 2. 3	2.4	
N1	2.5	2.6	2. 7	
R	2. 2	2.5	2.8	
S	8°			
S1		12°		
S2		15°		





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Revision History

Revision	Date	Major Changes
Preliminary	2024-8-27	Release of provisional version
ENG	2024-10-12	Release of engineering version

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qulified as astandard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

Scilicon Electric reserves the right to improve product design, function and reliability without notice.